NEC

SILICON TRANSISTOR ARRAY

μPA1437

PNP SILICON POWER TRANSISTOR ARRAY
LOW SPEED SWITCHING USE (DARLINGTON TRANSISTOR)
INDUSTRIAL USE

DESCRIPTION

The μPA1437 is PNP silicon epitaxial Darlington Power Transistor Array that built in 4 circuits designed for driving solenoid, relay, lamp and so on.

FEATURES

- Easy mount by 0.1 inch of terminal interval.
- High h_{FE} for Darlington Transistor.

ORDERING INFORMATION

Part Number	Package	Quality Grade
μPA1437H	10 Pin SIP	Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

ABSOLUTE MAXIMUM RATINGS (T_a = 25 °C)

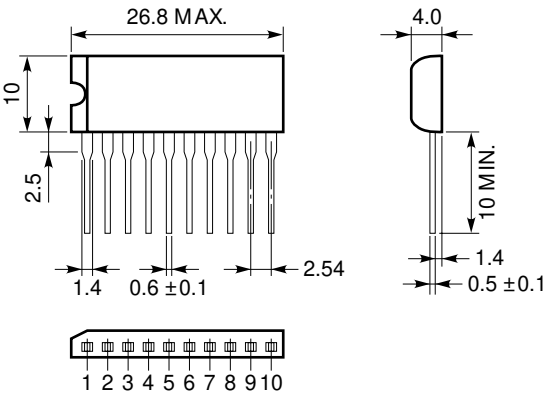
Collector to Base Voltage	V_{CBO}	–100	V
Collector to Emitter Voltage	V_{CEO}	–100	V
Emitter to Base Voltage	V_{EBO}	–7	V
Collector Current (DC)	$I_{C(DC)}$	∓3	A/unit
Collector Current (pulse)	$I_{C(pulse)}$*	∓6	A/unit
Base Current (DC)	$I_{B(DC)}$	–0.3	A/unit
Total Power Dissipation	P_{T1}**	3.5	W
Total Power Dissipation	P_{T2}***	28	W
Junction Temperature	T_j	150	°C
Storage Temperature	T_{stg}	–55 to +150	°C

* PW ≤ 300 μs, Duty Cycle ≤ 10 %

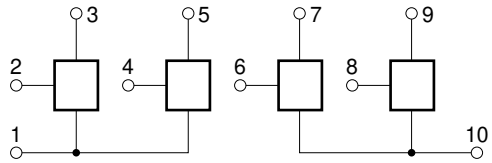
** 4 Circuits, T_a = 25 °C

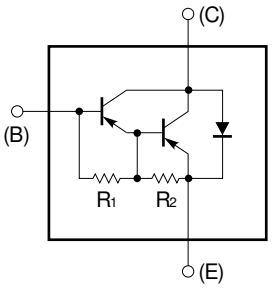
*** 4 Circuits, T_c = 25 °C

PACKAGE DIMENSION
(in millimeters)



CONNECTION DIAGRAM





PIN No.

2, 4, 6, 8: Base (B)
3, 5, 7, 9: Collector (C)
1, 10 : Emitter (E)

$R_1 \fallingdotseq 8.3\ k\Omega$
$R_2 \fallingdotseq 600\ \Omega$

The information in this document is subject to change without notice.

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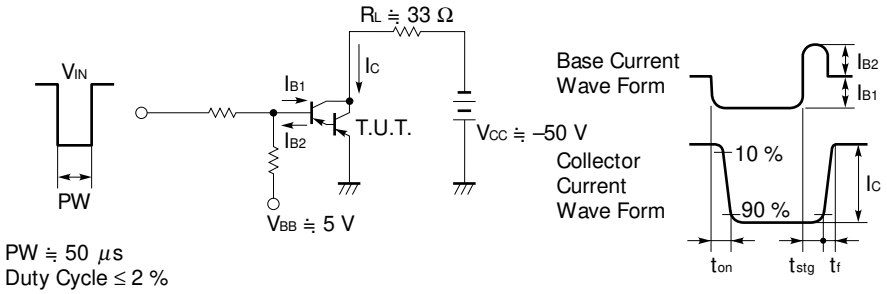
ELECTRICAL CHARACTERISTICS (T_a = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Collector to Emitter Sustaining Voltage	$V_{CEO(SUS)}$	–100			V	I_C = –1.5 A, I_B = –1.5 mA, L = 1 mH
Collector Leakage Current	I_{CBO}			–10	μA	V_{CB} = –100 V, I_E = 0
Emitter Leakage Current	I_{EBO}			–1	mA	V_{EB} = –5 V, I_C = 0
DC Current Gain	h_{FE1} *	1000			—	V_{CE} = –2 V, I_C = –0.5 A
DC Current Gain	h_{FE2} *	2000		20000	—	V_{CE} = –2 V, I_C = –1.5 A
Collector Saturation Voltage	$V_{CE(sat)}$ *		–0.9	–1.2	V	I_C = –1.5 A, I_B = –1.5 mA
Base Saturation Voltage	$V_{BE(sat)}$ *		–1.5	–2	V	I_C = –1.5 A, I_B = –1.5 mA
Turn On Time	t_{on}		1		μs	I_C = –1.5 A I_{B1} = –I_{B2} = –1.5 mA V_{CC} ≒ 50 V, R_L ≒ 33 Ω See test circuit
Storage Time	t_{stg}		3		μs	
Fall Time	t_f		1		μs	

* PW ≤ 350 μs, Duty Cycle ≤ 2 % / pulsed

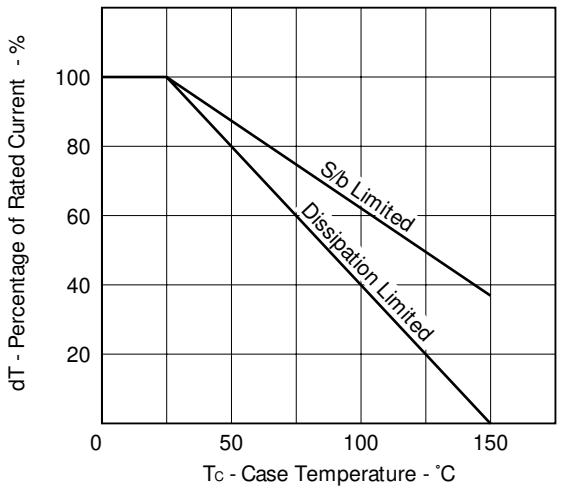
SWITCHING TIME TEST CIRCUIT



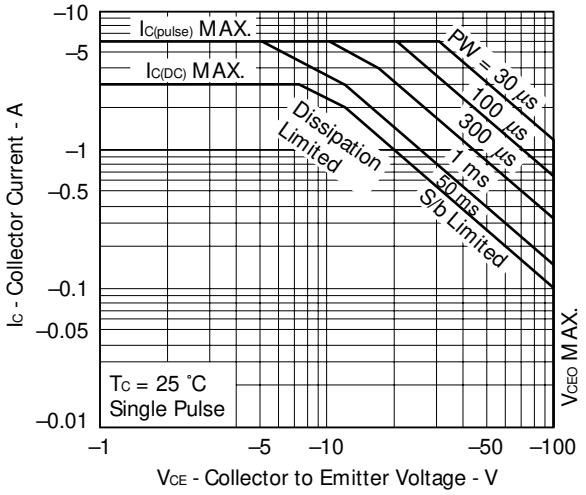
PW ≒ 50 μs
Duty Cycle ≤ 2 %

TYPICAL CHARACTERISTICS (T_a = 25 ˚C)

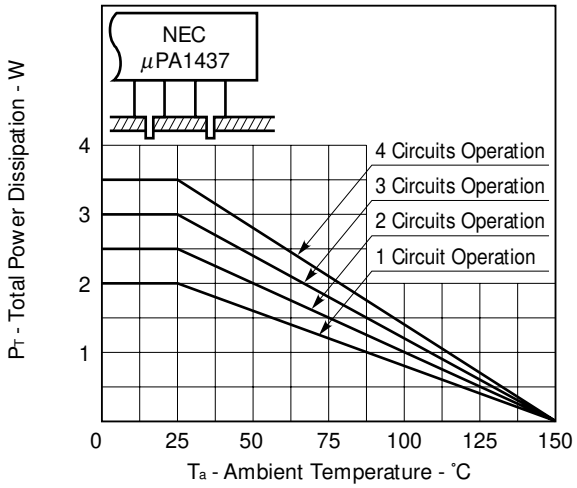
DERATING CURVE OF SAFE OPERATING AREA



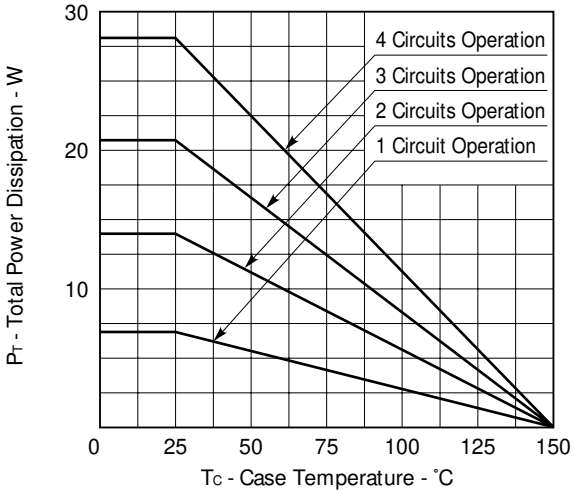
SAFE OPERATING AREA



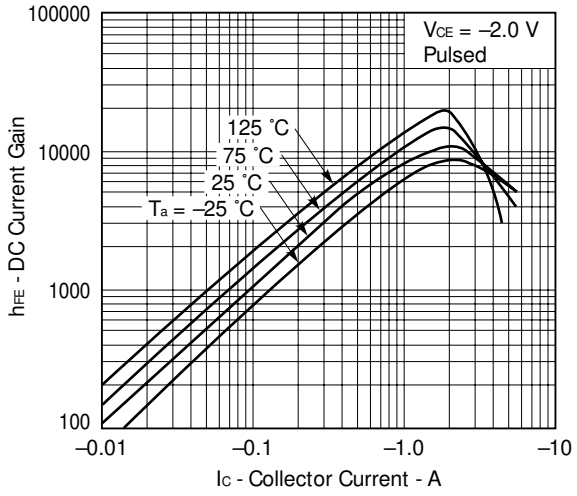
TOTAL POWER DISSIPATION vs. AMBIENT TEMPERATURE



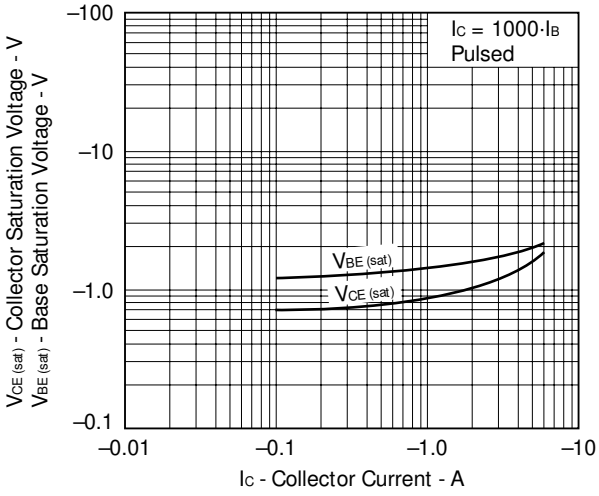
TOTAL POWER DISSIPATION vs. CASE TEMPERATURE



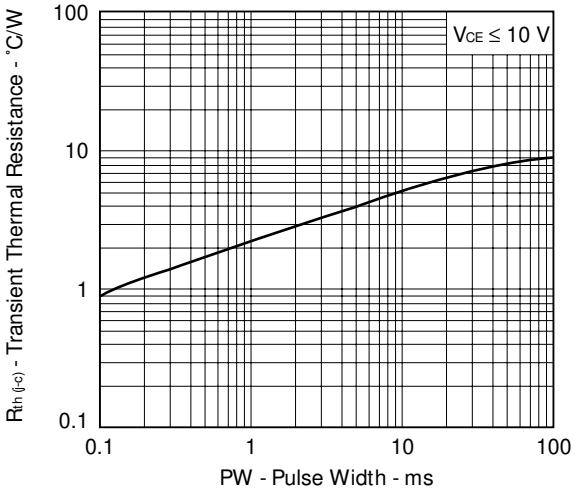
DC CURRENT GAIN vs. COLLECTOR CURRENT



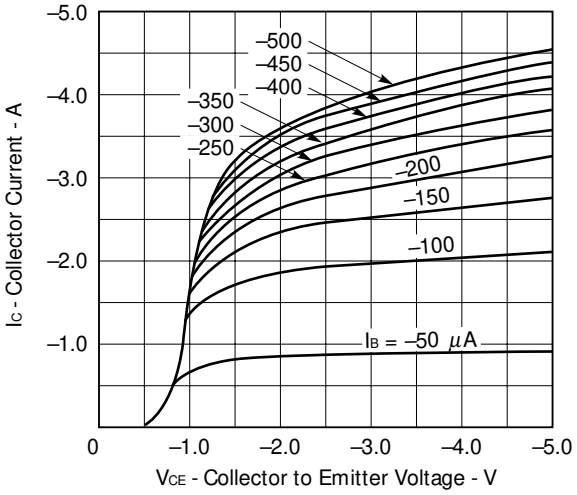
BASE AND COLLECTOR SATURATION VOLTAGE vs. COLLECTOR CURRENT



TRANSIENT THERMAL RESISTANCE



COLLECTOR CURRENT vs. COLLECTOR TO EMITTER VOLTAGE



REFERENCE

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134

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